PDC09D8BX

N-Ch 100V Fast Switching MOSFETs

Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

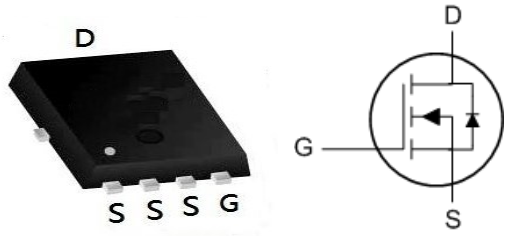
Product Summary

BVDSS	RDSON	ID
100V	3.5mΩ	130A

Applications

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

PDFN5060-8L Pin Configuration



Absolute Maximum Ratings（T_A = 25°C, unless otherwise noted）

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	T_C=25°C	I_D	130	A
	T_C=100°C		76	
Pulsed Drain Current[1]		I_{DM}	480	A
Single Pulse Avalanche Energy[2]		EAS	320	mJ
Total Power Dissipation	T_C=25°C	P_D	131.6	W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient[3]	$R_{\theta JA}$	48	°C/W
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	0.95	°C/W

Electrical Characteristics（T_J = 25°C, unless otherwise noted）

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 250μA	100	-	-	V
Gate-body Leakage current		I_{GSS}	V_{DS} = 0V, V_{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T_J=25℃	I_{DSS}	V_{DS} =100V, V_{GS} = 0V	-	-	1	μA
	T_J=100℃			-	-	100	
Gate-Threshold Voltage		$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	1.2	1.8	2.5	V
Drain-Source on-Resistance[4]		$R_{DS(on)}$	V_{GS} = 10V, I_D = 20A	-	3.5	4.5	mΩ
			V_{GS} = 4.5V, I_D = 15A	-	5.2	6.7	
Forward Transconductance[4]		g_{fs}	V_{DS} = 10V, I_D = 20A	-	70	-	S
Dynamic Characteristics[5]							
Input Capacitance		C_{iss}	V_{DS} = 50V, V_{GS} =0V, f =1MHz	-	5475	-	pF
Output Capacitance		C_{oss}		-	768	-	
Reverse Transfer Capacitance		C_{rss}		-	22	-	
Gate Resistance		R_g	f =1MHz	-	1.3	-	Ω
Switching Characteristics[5]							
Total Gate Charge		Q_g	V_{GS} = 10V, V_{DS} = 50V, I_D=20A	-	111.2	-	nC
Gate-Source Charge		Q_{gs}		-	17.5	-	
Gate-Drain Charge		Q_{gd}		-	30.2	-	
Turn-on Delay Time		$t_{d(on)}$	V_{GS} =10V, V_{DD} =50V, R_G = 3Ω, I_D= 20A	-	22.2	-	ns
Rise Time		t_r		-	37.8	-	
Turn-off Delay Time		$t_{d(off)}$		-	95.2	-	
Fall Time		t_f		-	35.6	-	
Body Diode Reverse Recovery Time		t_{rr}	I_F = 20A, dI/dt=100A/μs	-	59.4	-	ns
Body Diode Reverse Recovery Charge		Q_{rr}		-	91.8	-	nC
Drain-Source Body Diode Characteristics							
Diode Forward Voltage[4]		V_{SD}	I_S = 20A, V_{GS} = 0V	-	-	1.2	V
Continuous Source Current	T_C=25° C	I_S	-	-	-	130	A

Typical Characteristics

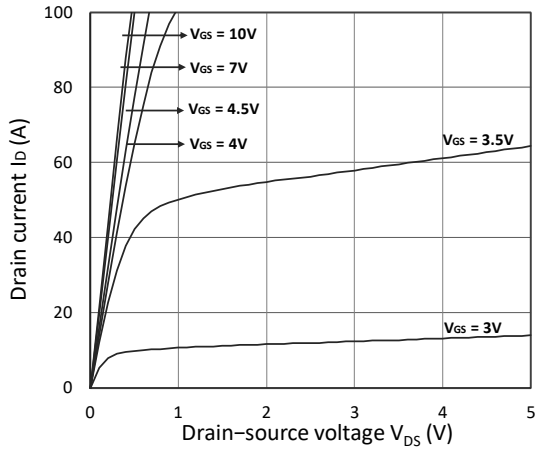


Figure 1. Output Characteristics

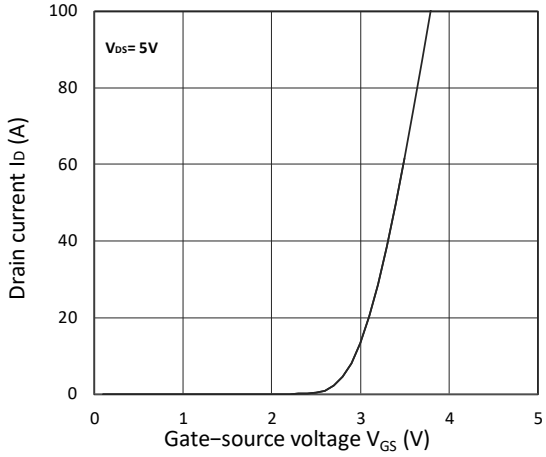


Figure 2. Transfer Characteristics

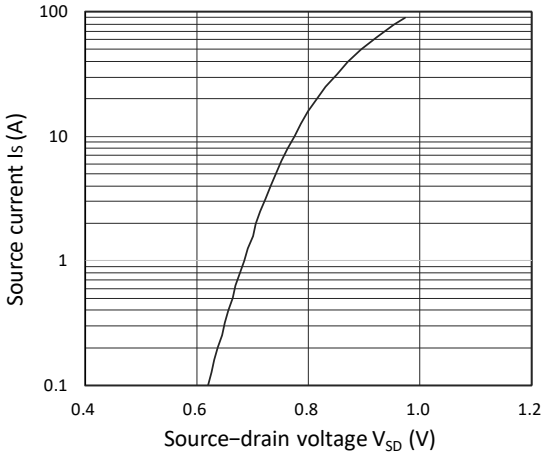


Figure 3. Forward Characteristics of Reverse

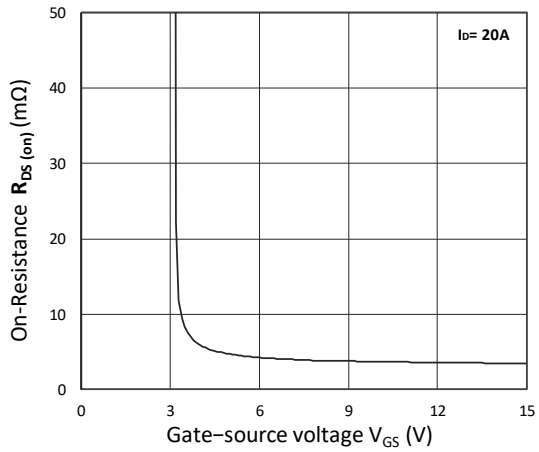


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

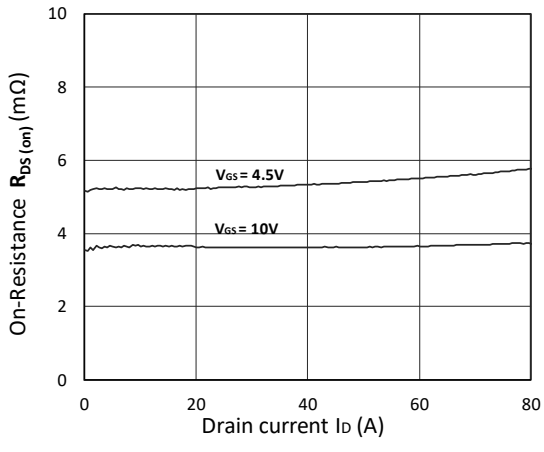


Figure 5. $R_{DS(ON)}$ vs. I_D

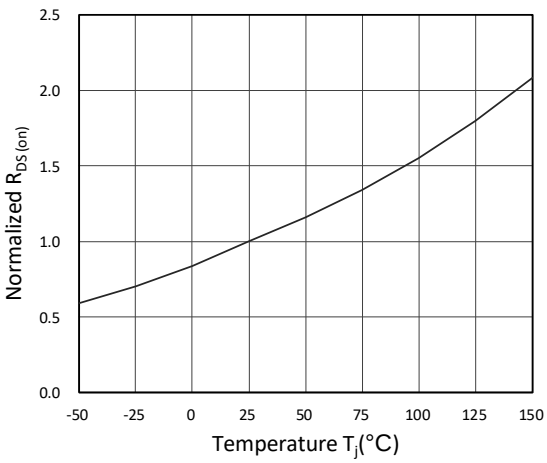


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

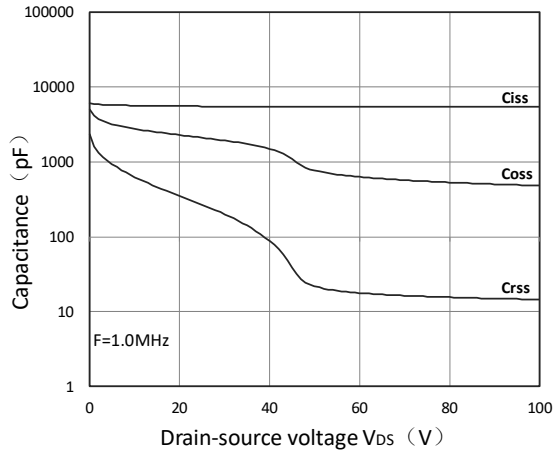


Figure 7. Capacitance Characteristics

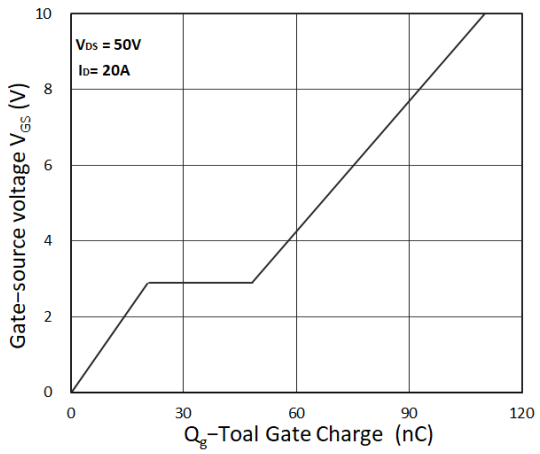


Figure 8. Gate Charge Characteristics

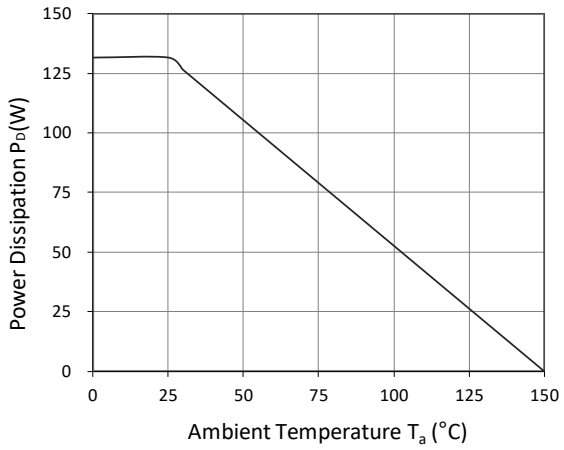


Figure 9. Power Dissipation

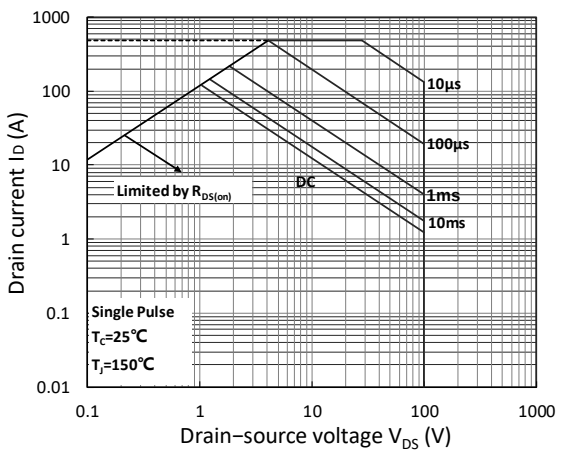


Figure10. Safe Operating Area

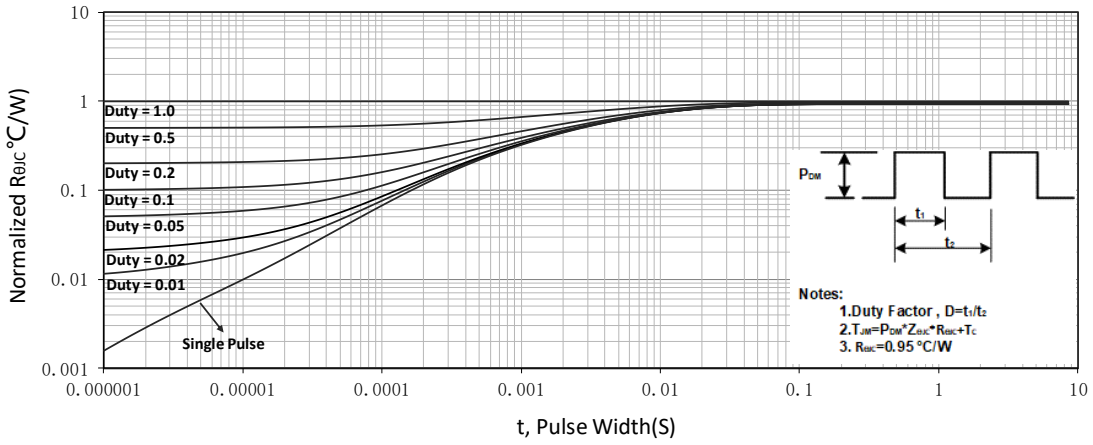


Figure 11. Normalized Maximum Transient Thermal Impedance

■ Test circuits and waveforms

Test Circuit

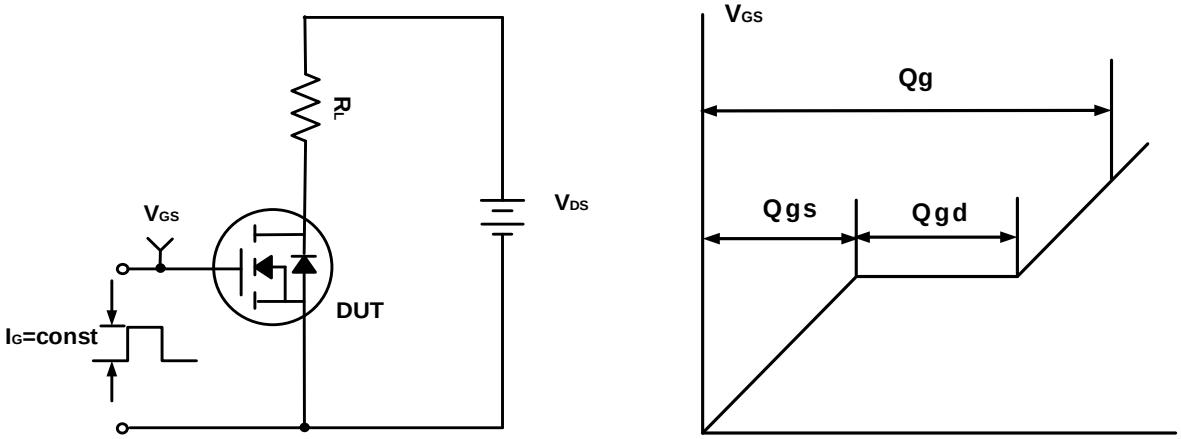


Figure A. Gate Charge Test Circuit & Waveforms

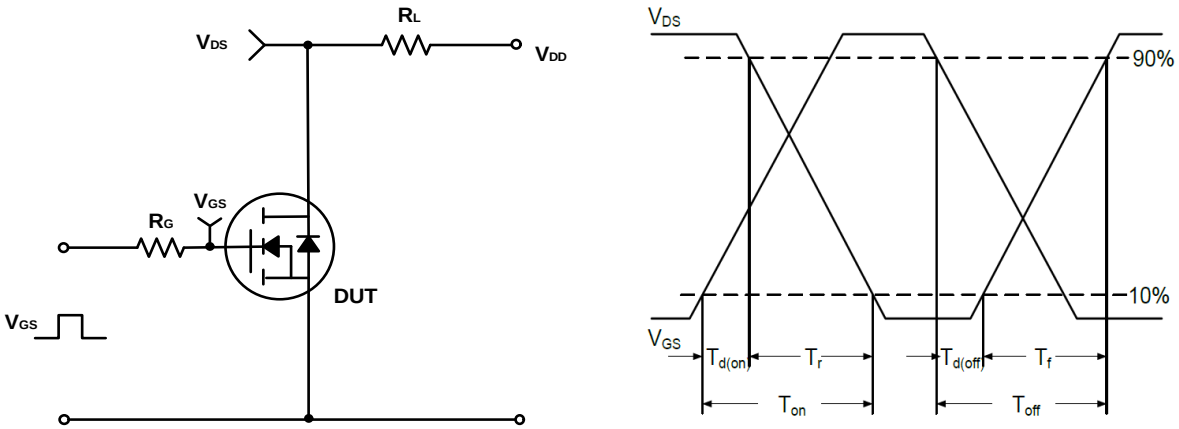


Figure B. Switching Test Circuit & Waveforms

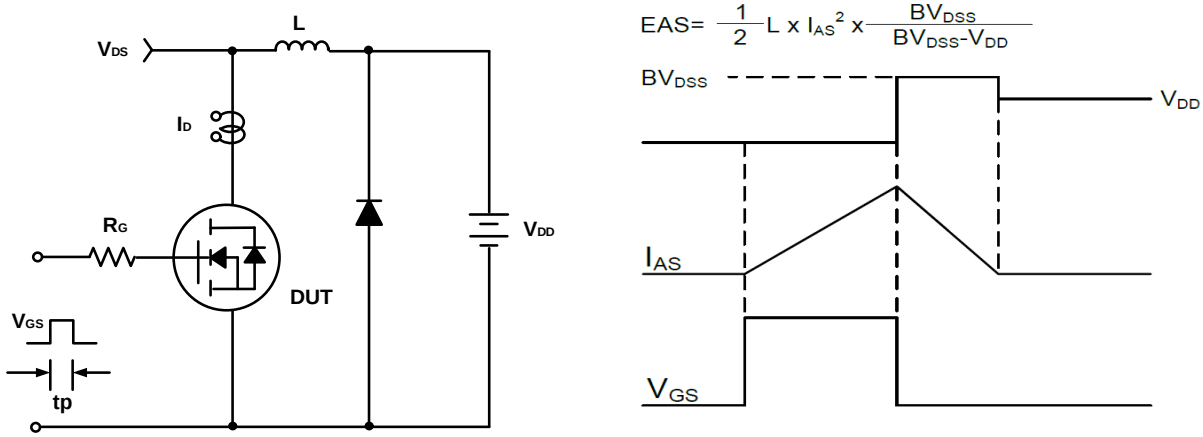
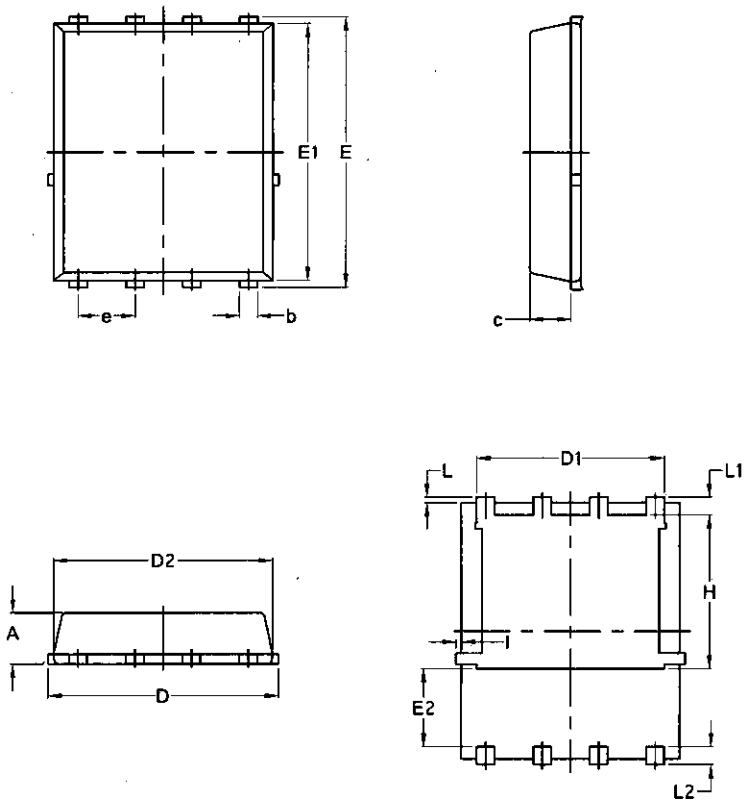


Figure C. Unclamped Inductive Switching Circuit & Waveforms

Package Mechanical Data-PDFN5060-8L-Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070